

ICTS- Integrated micro-nanofabrication CLEANROOM

LIDERAC – List of Equipment opened in Qualified Self-service Mode

CODE	Equipment Description	Area	contact	CMOS* Compatible
NL11	Optical Microscope Zeiss in nano area	Nanotechnologies	Xavier Borrisé	Mixed
NL12	SEM Zeiss Auriga 40 (outside de CR)	Nanotechnologies	Xavier Borrisé	No CMOS
NL21	AFM Bruker ICON	Nanotechnologies	Xavier Borrisé	Mixed
NL22	SEM Zeiss Gemini 560L	Nanotechnologies	Xavier Borrisé	Mixed
GH09	Quimipol Inmerson chemical bench	Wet etching	Nuria Torres	No CMOS
GH18	Tepla Gigabatch 360M O2 plasma asher	Wet etching	Nuria Torres	No CMOS
MS01	Glass cabinet	Microsystems	Marta Duch	Mixed
MS03	Critical Point Dryer Tousimis	Microsystems	Marta Duch	Mixed
MS04	Cabinet porous Si	Microsystems	Marta Duch	Mixed
MS05	Cabinet Electroplating	Microsystems	Marta Duch	Mixed
MS06	Oven Alco -P Selecta, MNC	Microsystems	Marta Duch	Mixed
MS07	Oven Heraeus UT6060, MNC	Microsystems	Marta Duch	Mixed
MS09	Leica magnifying glass	Microsystems	Marta Duch	Mixed
MS11	SB6 KarlSüss substrate bonder	Microsystems	Marta Duch	No CMOS
MS12/MS13	Chemical wet benches: KOH, lift-off ...	Microsystems	Marta Duch	Mixed
MS15	Spinner Laurell WS-400A.6NPP/LITE	Microsystems	Marta Duch	Mixed
MS16	Oven Thermo Scient, CMOS	Microsystems	Marta Duch	CMOS
MS17	Cabinet Quimipol	Microsystems	Marta Duch	Mixed
MS18	Microscope Leica	Microsystems	Marta Duch	Mixed
MS19	Drop Contact Angle Analyser DSA25E	Microsystems	Marta Duch	Mixed
MS20	3D Optical Profiler S Neox	Microsystems	Marta Duch	Mixed
PT10	PECVD Oxford Plasmalab 800 SiO SiN a-Si	Thermal Processes	Sara Durán	No CMOS

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FL07	Delta 80 Karl Suss spinner for SU-8	Photolithography	Javier Sánchez	Mixed
FL10	Karl Suss Ma/MB 6 2-sides aligner	Photolithography	Javier Sánchez	No CMOS
FL11	Hot Plates + fume Hood	Photolithography	Javier Sánchez	Mixed
FL12	Oven Heraeus UT606	Photolithography	Javier Sánchez	No CMOS
FL18	Delta 20 BLE - Spinner for PR and AZ	Photolithography	Javier Sánchez	Mixed
FL26	UV insolation SPECTRO	Photolithography	Javier Sánchez	No CMOS
FL28	SiC PR Spinner Larell 6NPP/Lite	Photolithography	Javier Sánchez	Mixed
FL33	GBC 3500 Laminator	Photolithography	Javier Sánchez	Mixed
FL36	Fume hood with developer Laurell	Photolithography	Javier Sánchez	No CMOS
FL41	Inspection Microscope ZEISS Axiotron	Photolithography	Javier Sánchez	Mixed
FL45	Spinner Polyimide Laurell 23NPPB	Photolithography	Javier Sánchez	No CMOS
FL47	Kloe Dilease 650 Laser Writer	Photolithography	Javier Sánchez	Mixed
FL49	Hotplate with temperature regulator and sensor	Photolithography	Javier Sánchez	Mixed
FL53	Spinner Special Processes Laurell 23NPPB	Photolithography	Javier Sánchez	No CMOS
FL55	Hotplate for 6" wafers	Photolithography	Javier Sánchez	Mixed
VM03	4 puntas MNC ChangM	Inspection&Meas	Miguel Zabala	No CMOS
VM13	Nanospec 6100UV/Vis Reflectometer	Inspection&Meas	Miguel Zabala	Mixed
VM14	Wafer thickness Proforma 300	Inspection&Meas	Miguel Zabala	Mixed
VM18	Tencor P7 Stylus Profiler	Inspection&Meas	Miguel Zabala	No CMOS
VM19	Horiba Jobin Ivon/AugoSE Ellipsometer	Inspection&Meas	Miguel Zabala	Mixed
VM20	Optical inspection OM Leica DM8000	Inspection&Meas	Miguel Zabala	Mixed
VM21	FTIR INVENIO S	Inspection&Meas	Miguel Zabala	Mixed
VM22	Raman spectrometer Horiba XploRa	Inspection&Meas	Miguel Zabala	No CMOS
GS07	RIE-ICP Alcatel AMS110	Dry Etching	Roser Mas	No CMOS
GS11	Sentech MNC	Dry Etching	Roser Mas	No CMOS

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CODE	Equipment Description	Area	contact	CMOS* Compatib
CE01	Capacitance meter HP4280A	Electrical Characterization	Sergi Sánchez	Mixed
CE02	Capacitance meter HP4192A	Electrical Characterization	Sergi Sánchez	Mixed
CE03	pA Meter HP4140B	Electrical Characterization	Sergi Sánchez	Mixed
CE05/CE15	Keithley 4200-SCS Semiconductor Parameter Analyzer + Wafer Prober	Electrical Characterization	Sergi Sánchez	CMOS
CE06	Parameter analyzer HP4155B	Electrical Characterization	Sergi Sánchez	Mixed
CE07	Nanovolt meter K2182	Electrical Characterization	Sergi Sánchez	Mixed
CE08	Source meter K2636	Electrical Characterization	Sergi Sánchez	Mixed
CE09	Electrometer K6514	Electrical Characterization	Sergi Sánchez	Mixed
CE10	Oscilloscope LeCroy	Electrical Characterization	Sergi Sánchez	Mixed
CE16	Parametrical prober PA200	Electrical Characterization	Sergi Sánchez	Mixed
CE17	Keysight E4990A Impedance analyser	Electrical Characterization	Sergi Sánchez	Mixed
CE18	Parameter analyzer K4200-SCS	Electrical Characterization	Sergi Sánchez	Mixed
CE19	Parameter analyzer Keysight B1500	Electrical Characterization	Sergi Sánchez	Mixed
CE20	Test Probeshield MPI TS-2000SE	Electrical Characterization	Sergi Sánchez	Mixed
CE21	Power supply Promax FAC-662B	Electrical Characterization	Sergi Sánchez	Mixed
CE22	Data adquisition HP34970A	Electrical Characterization	Sergi Sánchez	Mixed
CE23	High Voltage SourceMeter K2470	Electrical Characterization	Sergi Sánchez	Mixed
CE24	Prober MPI Thermal TS-2000SE	Electrical Characterization	Sergi Sánchez	Mixed

(*) Note:

The Clean Room (CR) has a CMOS technology acting as a reference, so that appropriate cleaning and contaminationfree conditions must be observed. The same applies to a set of other CMOS-compatible or CMOS-like existing technologies. Therefore, potential risks of contamination of equipment, tools and environment must be avoided. Those risks are basically of two types: a) alkali metal ions (Na, K) and b) contaminant metals like some noble metals (Au, Pt, Cu, Pd, Ag)